



SOT724-1

plastic shrink small outline package; 20 leads; body width 3.9 mm; lead pitch 0.635 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SSOP20
Package type industry code	SSOP20
Package style descriptive code	SSOP (shrink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-137
Mounting method type	S (surface mount)
Issue date	18-2-2003

Table 1. Package summary

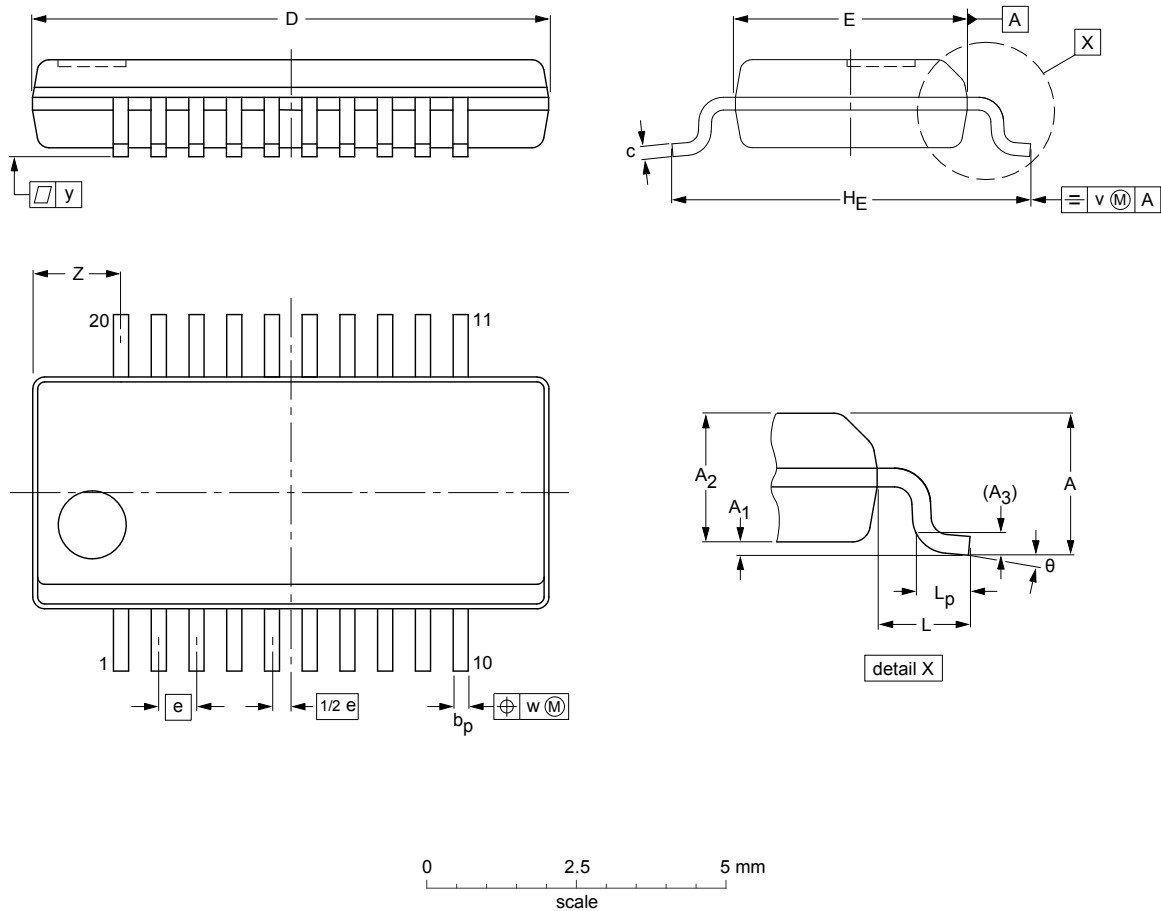
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	8.6	-	8.7	8.8	mm
E	package width	3.8	-	3.9	4	mm
A	seated height	[tbd]	-	1.73	1.73	mm
A ₂	package height	1.4	-	1.47	1.55	mm
n ₂	actual quantity of termination	-	-	20	-	



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2. Package outline

SSOP20: plastic shrink small outline package; 20 leads; body width 3.9 mm; lead pitch 0.635 mm SOT724-1



DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	v	w	y	Z ⁽¹⁾	θ
mm	1.73	0.25 0.10	1.55 1.40	0.25	0.31 0.20	0.25 0.18	8.8 8.6	4.0 3.8	0.635	6.2 5.8	1	0.89 0.41	0.25	0.18	0.1	1.67 1.28	8° 0°

Note

1. Plastic or metal protrusions of 0.2 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT724-1		MO-137				01-07-04 03-02-18

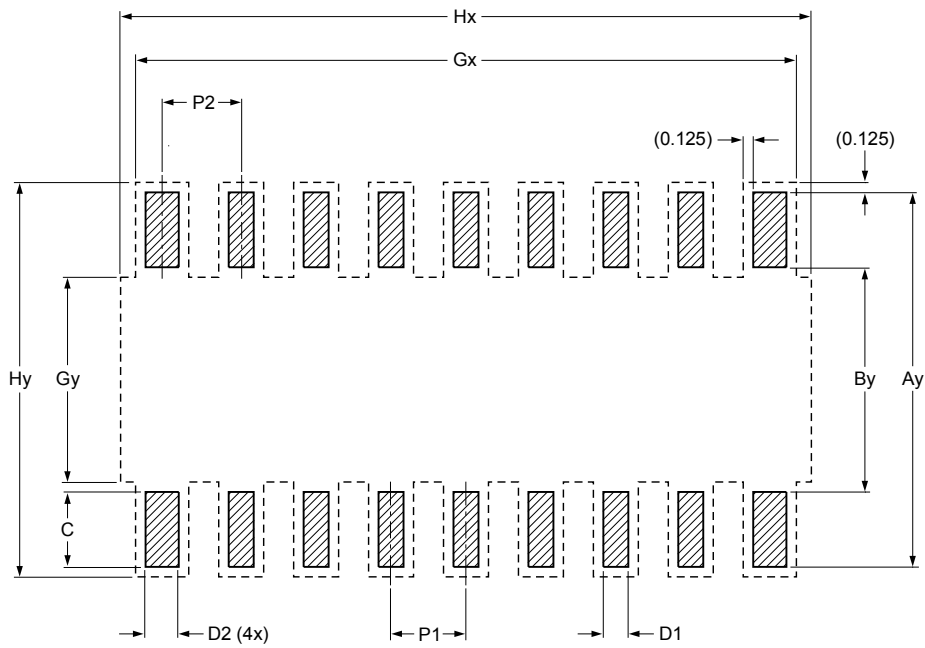
Fig. 1. Package outline SSOP20 (SOT724-1)

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3. Soldering

Footprint information for reflow soldering of SSOP20 package

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Generic footprint pattern
Refer to the package outline drawing for actual layout

 solder land
- - - - occupied area

DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.635	0.660	6.600	4.200	1.200	0.450	0.500	6.515	4.500	9.300	6.850

tot724-1_fr

Fig. 2. Reflow soldering footprint for SSOP20 (SOT724-1)

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4. Legal information

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